

# **Special issue on Novel Materials and Sensing Technologies on Electronic and Mechanical Devices**

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## **Special Issue Information**

Dear Colleagues,

In recent years, applications of novel materials and sensing technologies in electronic and mechanical devices have become rapidly developing fields. Manufacturing is the economic lifeline of a country and has been regarded as a labor-intensive industry. Therefore, to cut production costs, devices for internet of things (IoT) are widely developed. IoT is composed of the most integrated end devices and facilities, such as intelligent sensors for internal control, industrial systems, mobile terminal systems, floor control systems, and home intelligent facilities. Smart devices and external control information are utilized with hope to attract companies that manufacture high-value-added aerospace, automotive, IT mold, textile, optoelectronic, watch, medical, defense-related, automation, energy, and semiconductor-related parts and components to drive the country's economy. Therefore, the key to keeping up with the competitive advantage of domestic manufacturing in the future is still to rely on the development of advanced manufacturing and precision machinery-related technologies. The scope of this Special Issue "Novel Materials and Sensing Technologies on Electronic and Mechanical Devices" covers fundamental materials of electronic, mechanical, and electrical engineering, including their synthesis engineering, integration with many elements, designs of electronic or optical devices, evaluation of various performance characteristics, and exploration of their broad applications to

industry, environmental control, materials analyses, and so forth. We invite researchers to contribute their original research articles, as well as review articles, that will stimulate the continuing effort to understand the electronic and mechanical devices and optical sensors. Potential topics include but are not limited to the following:

- properties of electronic devices and optical sensors,
- advanced materials with new electronic and optical properties,
- advanced materials for preparation and applications,
- subjects related to electronic thin films and coating technology,
- synthesis engineering of advanced materials,
- advanced materials in mechatronic applications,
- Internet of things (IoT) on sensors,
- medical and health devices (e.g., wearable and implantable) on sensors,
- remote sensing, and
- sensors on robotics.

### **Schedule**

Manuscript due:	December 31, 2020
First round of reviews:	January 31, 2021
Second round of reviews:	March 1, 2021
Acceptance of final papers:	March 31, 2021
Publication (planned):	May 31, 2021

### **(Attention)**

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–15000 for electronic proofreading), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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